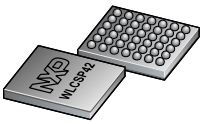

SOT1459-8

WLCSP42, wafer level chip scale package, 42 terminals, 0.4 mm pitch, 3.02 mm x 2.72 mm x 0.525 mm body (backside coating included)

11 December 2020 **Package information**

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP42
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	03-12-2020
Manufacturer package code	98ASA01726D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.69	2.72	2.75	mm
package width	2.99	3.02	3.05	mm
package height	-	0.525	0.565	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	42	-	

WLCSP42, wafer level chip scale package, 42 terminals, 0.4 mm pitch, 3.02 mm x 2.72 mm x 0.525 mm body (backside coating included)

2 Package outline

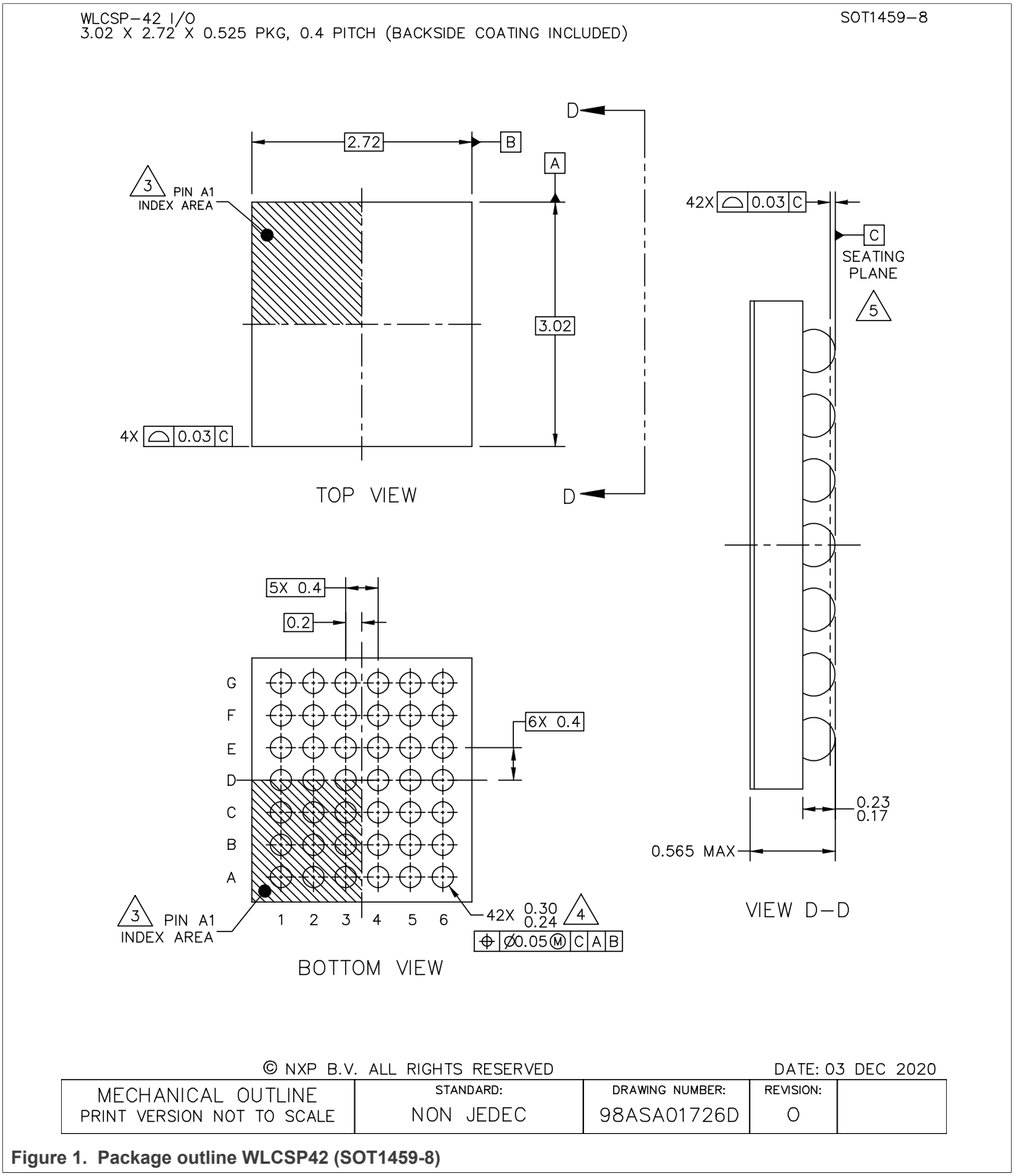

Figure 1. Package outline WLCSP42 (SOT1459-8)

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3 Soldering

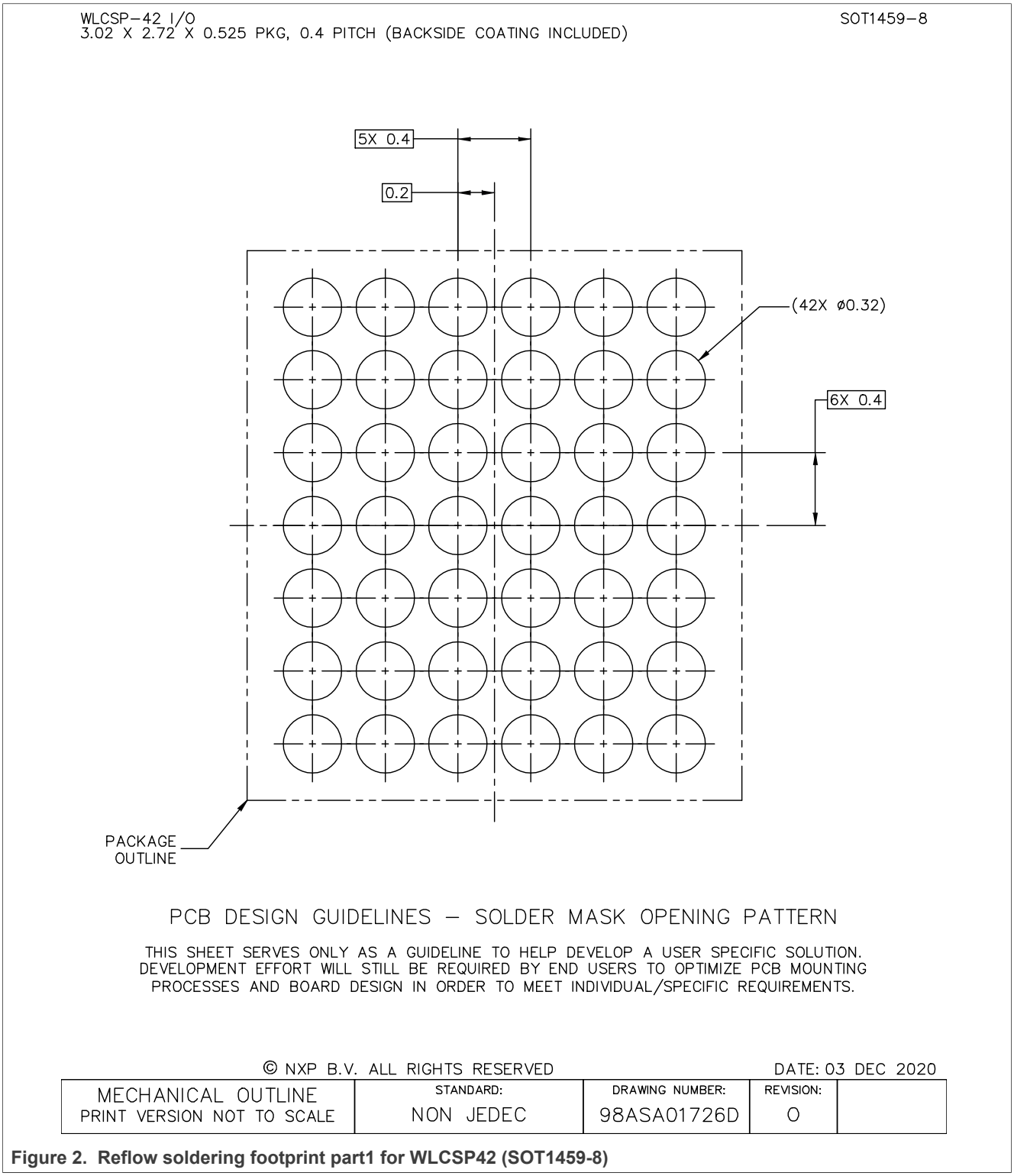

Figure 2. Reflow soldering footprint part1 for WLCSP42 (SOT1459-8)

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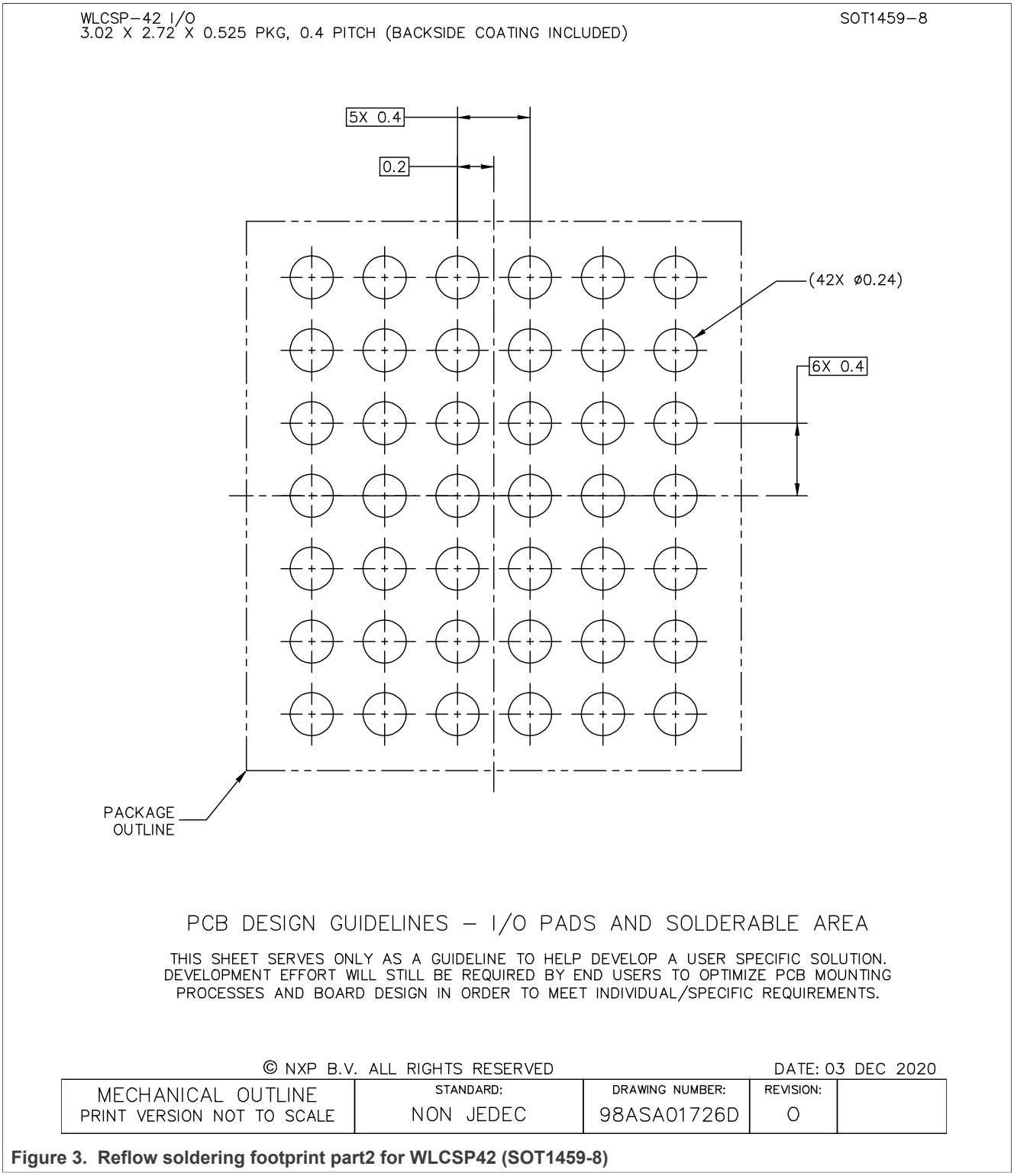

Figure 3. Reflow soldering footprint part2 for WLCSP42 (SOT1459-8)

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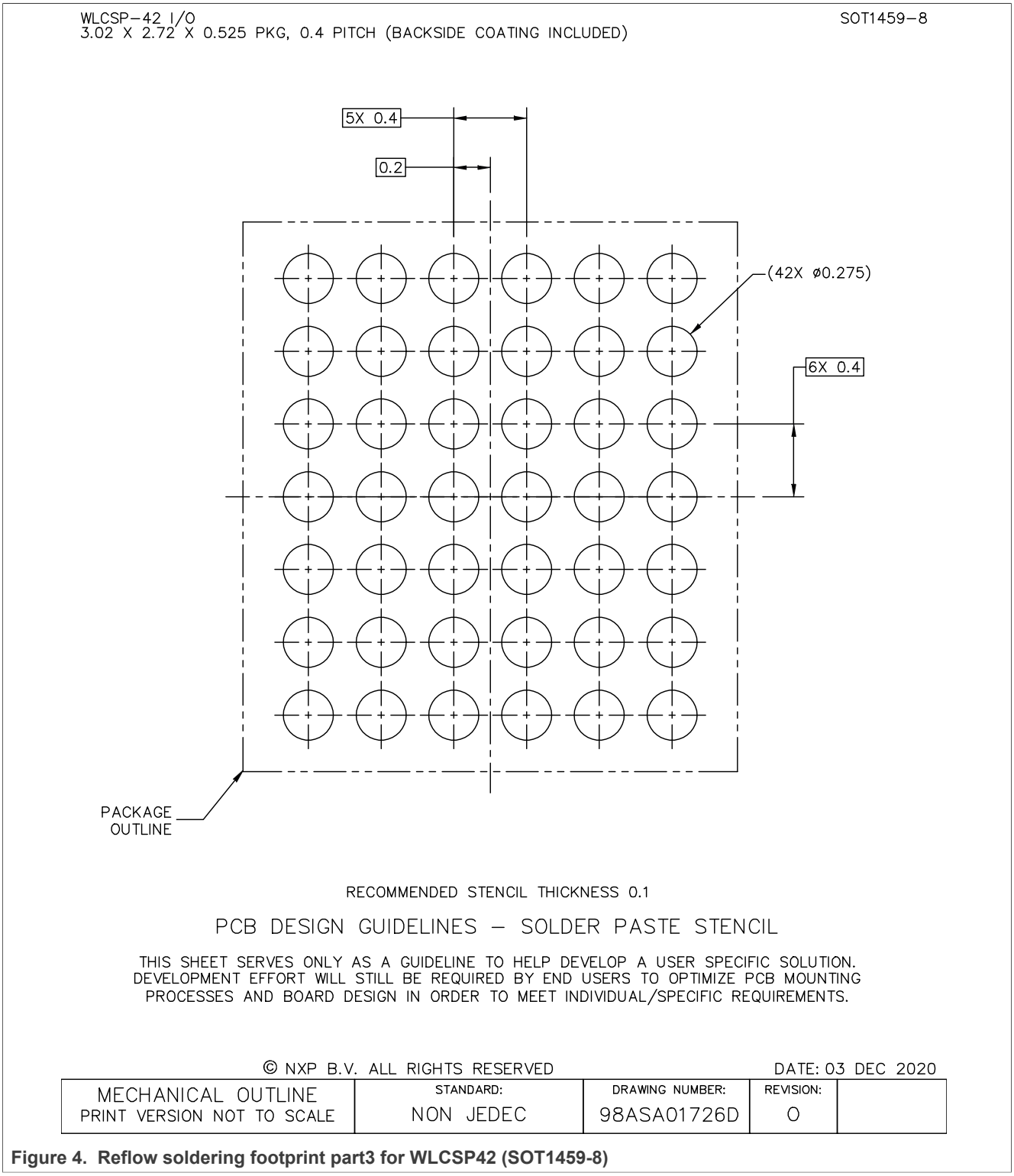

Figure 4. Reflow soldering footprint part3 for WLCSP42 (SOT1459-8)

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WLCSP42, wafer level chip scale package, 42 terminals, 0.4 mm pitch, 3.02 mm x 2.72 mm x 0.525 mm body (backside coating included)

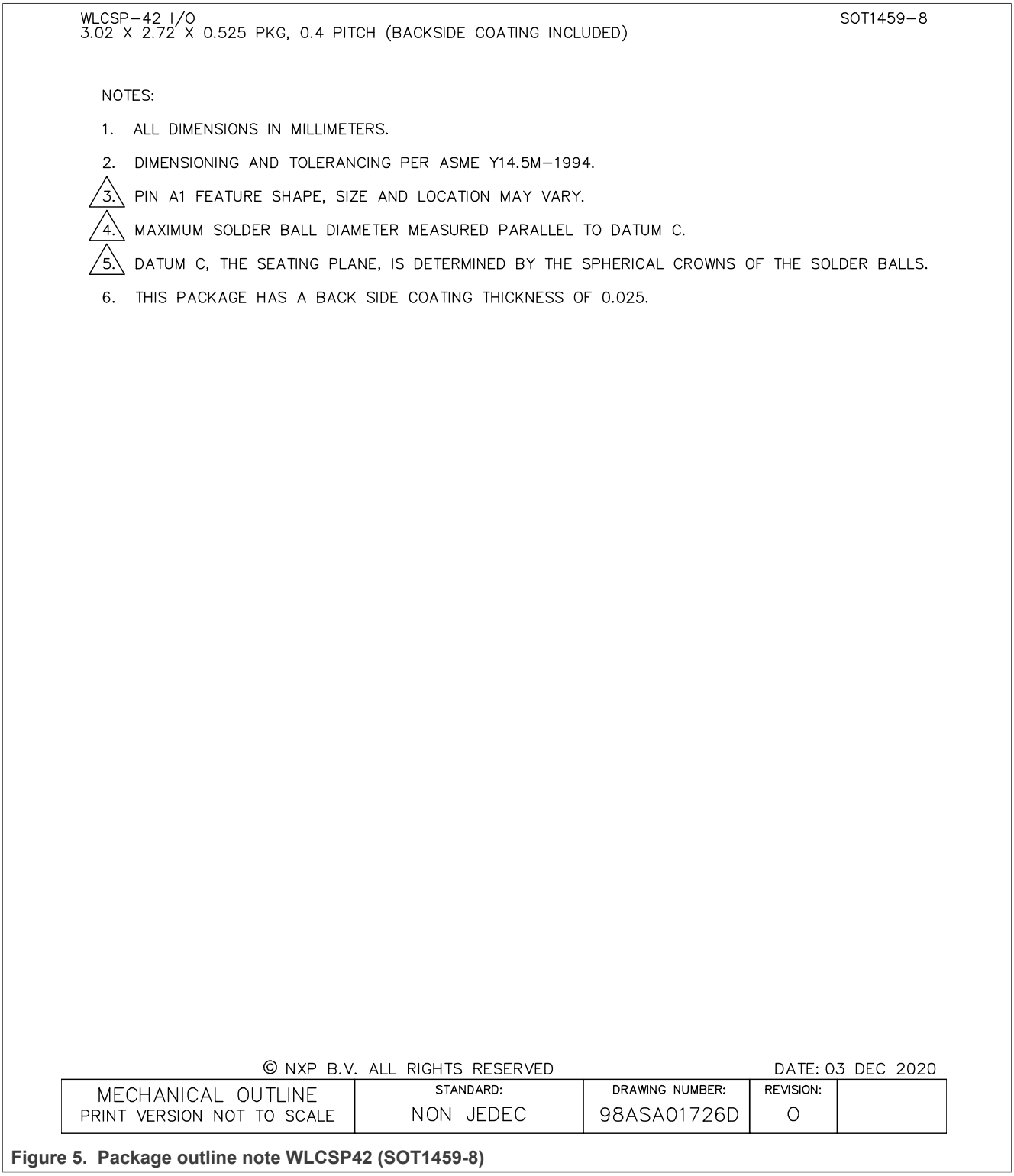

Figure 5. Package outline note WLCSP42 (SOT1459-8)

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WLCSP42, wafer level chip scale package, 42 terminals, 0.4 mm pitch, 3.02 mm x 2.72 mm x 0.525 mm body (backside coating included)

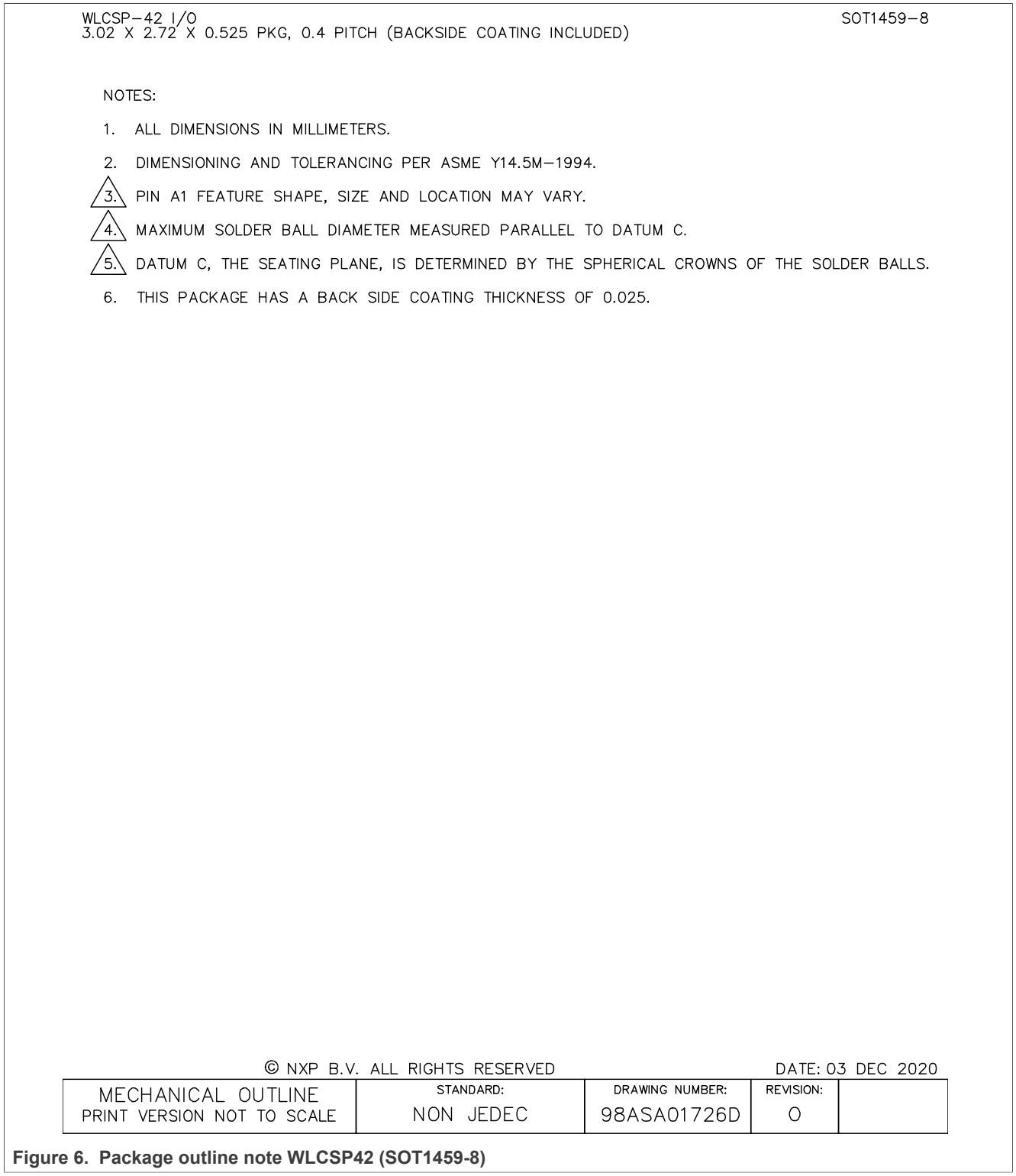

Figure 6. Package outline note WLCSP42 (SOT1459-8)

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WLCSP42, wafer level chip scale package, 42 terminals, 0.4 mm pitch, 3.02 mm x 2.72 mm x 0.525 mm body (backside coating included)

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